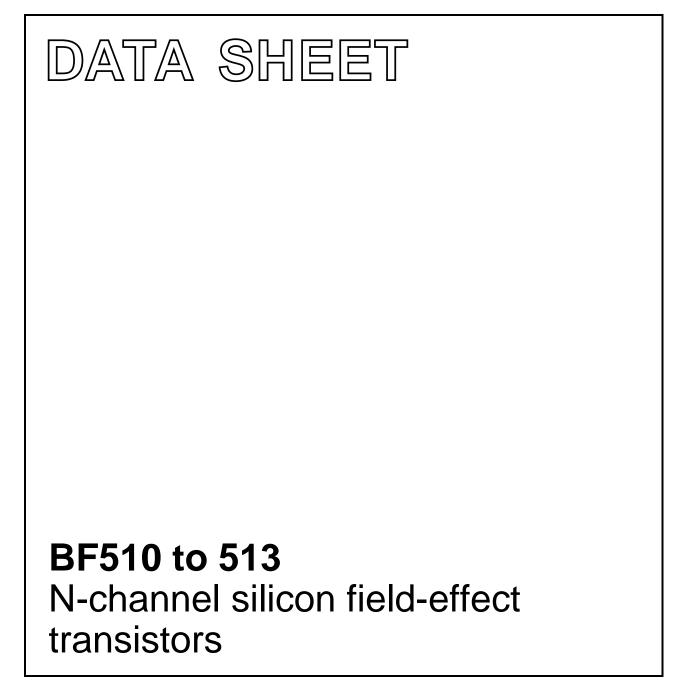
DISCRETE SEMICONDUCTORS



Product specification

December 1997



DESCRIPTION

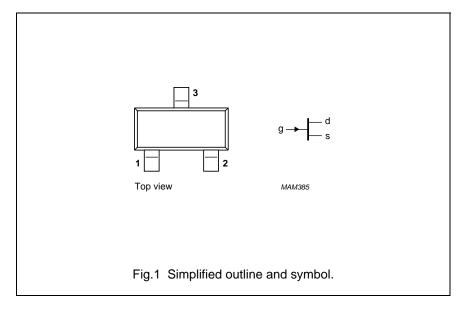
Asymmetrical N-channel planar epitaxial junction field-effect transistors in the miniature plastic envelope intended for applications up to the v.h.f. range in hybrid thick and thin-film circuits. Special features are the low feedback capacitance and the low noise figure. These features make the product very suitable for applications such as the r.f. stages in f.m. portables (BF510), car radios (BF511) and mains radios (BF512) or the mixer stage (BF513).

PINNING - SOT23

- 1 = gate
- 2 = drain
- 3 = source

MARKING CODE

BF510 = S6p BF511 = S7p BF512 = S8p BF513 = S9p



QUICK REFERENCE DATA

Drain-source voltage	V_{DS}	max.		2	20		V
Drain current (DC or average)	I _D	max.		3	30		mA
Total power dissipation							
up to $T_{amb} = 40 \ ^{\circ}C$	P _{tot}	max.		25	50		mW
			BF510	511	512	513	
Drain current		>	0.7	2.5	6	10	mA
$V_{DS} = 10 V; V_{GS} = 0$	I_{DSS}	<	3.0	7.0	12	18	mA
Transfer admittance (common source) $V_{DS} = 10 \text{ V}; \text{ V}_{GS} = 0; \text{ f} = 1 \text{ kHz}$ Feedback capacitance	y _{fs}	>	2.5	4	6	7	mS
V _{DS} = 10 V; V _{GS} = 0	C _{rs}	typ.	0.3	0.3	_	_	pF
$V_{DS} = 10 \text{ V}; \text{ I}_{D} = 5 \text{ mA}$ Noise figure at optimum source admittance	C_{rs}	typ.	_	-	0.3	0.3	pF
G _S = 1 mS; –B _S = 3 mS; f = 100 MHz							
$V_{DS} = 10 \text{ V}; V_{GS} = 0$	F	typ.	1.5	1.5	-	_	dB
$V_{DS} = 10 \text{ V}; \text{ I}_{D} = 5 \text{ mA}$	F	typ.	_	-	1.5	1.5	dB

BF510 to 513

Limiting values in accordance with the Absolute Maximum System (IEC 134) Drain-source voltage V_{DS} 20 V max. Drain-gate voltage (open source) 20 V V_{DGO} max. 30 mA Drain current (DC or average) I_D max. Gate current 10 mA $\pm I_G$ max. Total power dissipation up to $T_{amb} = 40 \text{ °C}$ (note 1) P_{tot} 250 mW max. Storage temperature range -65 to + 150 °C T_{stg} Junction temperature Τį max. 150 °C THERMAL RESISTANCE

From junction to amplent (note 1) $R_{th j-a} = 430 \text{ K/v}$	From junction to ambient (note 1)	R _{th j-a}	=	430 K/W
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Note

1. Mounted on a ceramic substrate of 8 mm \times 10 mm \times 0.7 mm.

STATIC CHARACTERISTICS

 $T_{amb} = 25 \ ^{\circ}C$

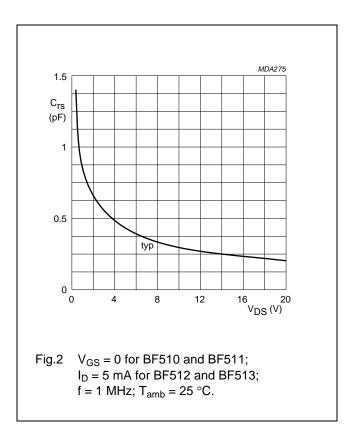
			BF510	511	512	513	
Gate cut-off current							
$-V_{GS} = 0.2 \text{ V}; V_{DS} = 0$	-I _{GSS}	<	10	10	10	10	nA
Gate-drain breakdown voltage							
$I_{S} = 0; -I_{D} = 10 \ \mu A$	-V _{(BR)GDO}	>	20	20	20	20	V
Drain current V _{DS} = 10 V; V _{GS} = 0	I _{DSS}	> <	0.7 3.0	2.5 7.0	6 12	-	mA mA
Gate-source cut-off voltage $I_D = 10 \ \mu A; V_{DS} = 10 \ V$	-V _{(P)GS}	typ.	0.8	1.5	2.2	3	V

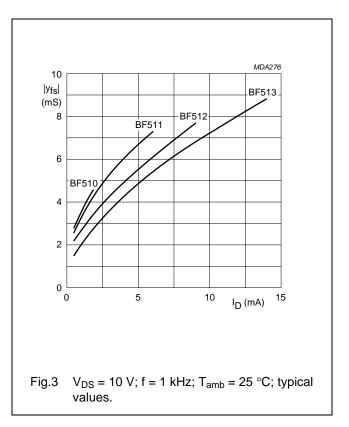
Product specification

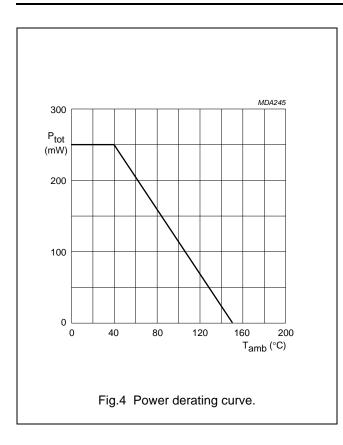
N-channel silicon field-effect transistors

DYNAMIC	CHARACTERISTICS	

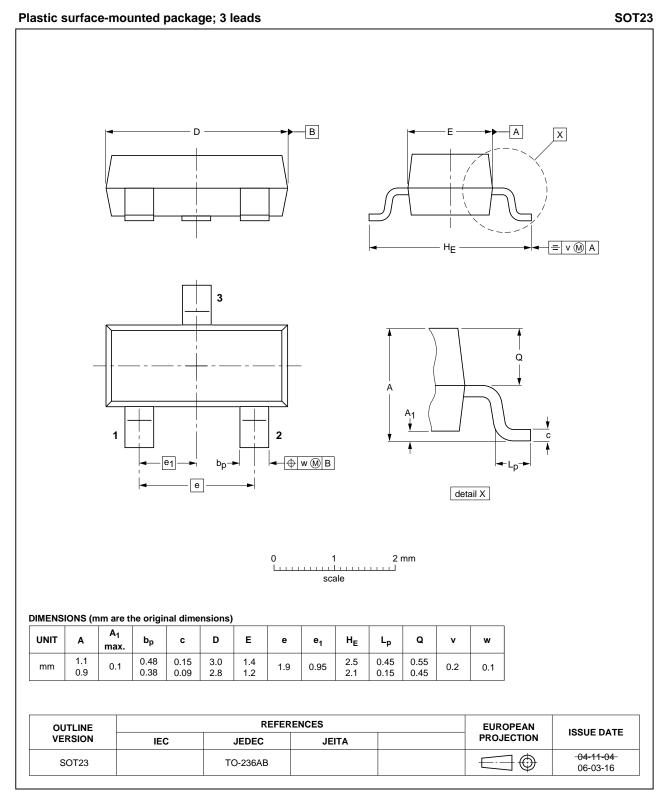
Measuring conditions (common source):	V_{DS} = 10 V; V_{GS} = 0; T_{amb} = 25 °C for BF510 and BF511						
	V_{DS} = 10 V; I_{D} = 5 mA; T_{amb} = 25 °C for BF512 and BF513						
y-parameters (common source)		_	BF510	511	512	513	
Input capacitance at f = 1 MHz	C _{is}	<	5	5	5	5	pF
Input conductance at f = 100 MHz	g is	typ.	100	90	60	50	μS
Feedback capacitance at f = 1 MHz	C	typ.	0.4	0.4	0.4	0.4	pF
recuback capacitance at r = r winz	C _{rs}	<	0.5	0.5	0.5	0.5	pF
Transfer admittance at f = 1 kHz	y _{fs}	>	2.5	4.0	4.0	3.5	mS
$V_{GS} = 0$ instead of $I_D = 5 \text{ mA}$	y _{fs}	>	-	-	6.0	7.0	mS
Transfer admittance at f = 100 MHz	y _{fs}	typ.	3.5	5.5	5.0	5.0	mS
Output capacitance at f = 1 MHz	C _{os}	<	3	3	3	3	pF
Output conductance at f = 1 MHz		<	60	80	100	120	μS
Output conductance at f = 100 MHz	g os	typ.	35	55	70	90	μS
Noise figure at optimum source admittance							
$G_{S} = 1 \text{ mS}; -B_{S} = 3 \text{ mS};$							
f = 100 MHz	F	typ.	1.5	1.5	1.5	1.5	dB







PACKAGE OUTLINE



December 1997

BF510 to 513

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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BF510 to 513

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Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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